

SID

Factory: Rot am See

Article:

551

ML8

Provided:

Kracht, Enrico

Customer:

Date:

29.09.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	175		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.51mm-018+018-TG150-HF	50200855	18	L2		A01
		510		4	
		18	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	165		5	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6	
A-RS-FR4-ML-0.51mm-018+018-TG150-HF	50200855	18	L4		A02
		510		7	
		18	L5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	165		8	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		9	
A-RS-FR4-ML-0.51mm-018+018-TG150-HF	50200855	18	L6		A03
		510		10	
		18	L7		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	175		11	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		12	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2354 µm

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